### **Inductors**

# For General Applications SMD

**FEATURES** 

- As multilayer chip inductor using ferrite material, it is the first narrow tolerance(±5%) small inductor in the industry.
- This inductor is complete by E-12 series to 0.1-4.7μH.
- Inductance change by soldering is less than 1/3 from elegance conventionally.
- Maintains the same dimensions and electrical characteristics as that of the conventional MLF series.
- The products contain no lead and also support lead-free soldering.

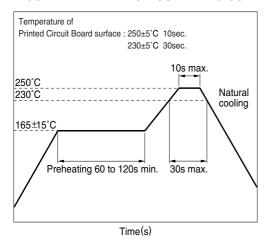
#### **APPLICATIONS**

Signal processing such as car audio, automotive (intended) use, tuner.

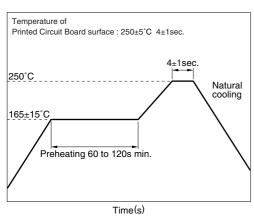
#### **SPECIFICATIONS**

Operating temperature range	−55 to +125°C
Storage temperature range	-55 to +125°C[Unit of products]

#### RECOMMENDED REFLOW SOLDERING CONDITIONS



#### RECOMMENDED FLOW SOLDERING CONDITIONS



### MLF Series MLF2012-J Type

#### PRODUCT IDENTIFICATION

 $\frac{\text{MLF}}{(1)} \; \frac{2012}{(2)} \; \frac{\text{A}}{(3)} \; \frac{1\text{R0}}{(4)} \; \frac{\text{J}}{(5)} \; \frac{\text{T}}{(6)}$ 

- (1) Series name
- (2) Dimensions L×W

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2012	2.0×1.25mm	

- (3) Material code
- (4) Inductance value

R10	0.1μΗ	
1R0	1.0μΗ	
100	10μΗ	

(5) Inductance tolerance

J	+5%	

(6) Packaging style

T Taning [reel]	
i i aping peer	

#### **PACKAGING STYLE AND QUANTITIES**

Packaging style	Product's thickness T	Quantity
Taping	0.85mm	4000 pieces/reel
Taping	1.25mm	2000 pieces/reel

#### HANDLING AND PRECAUTIONS

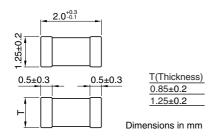
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and product temperature does not exceed 150°C.
- After mounting components onto the printed circuit board, do not apply stress through board bending or mishandling.
- The inductance value may change due to magnetic saturation if the current exceeds the rated maximum.
- Do not expose the inductors to stray magnetic fields.
- · Avoid static electricity discharge during handling.
- When hand soldering, apply the soldering iron to the printed circuit board only. Temperature of the iron tip should not exceed 300°C. Soldering time should not exceed 3 seconds.

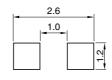
## **Inductors**

# MLF Series MLF2012-J Type

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#### SHAPES AND DIMENSIONS/RECOMMENDED PC BOARD PATTERN



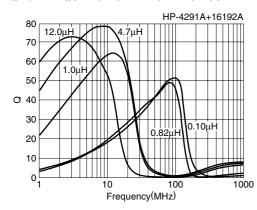




#### **ELECTRICAL CHARACTERISTICS**

Part No.	Inductance (μΗ)	Inductance tolerance	Q min.	Self-resonant frequency min.(MHz)	DC resistance max.(Ω)	Rated current max. (mA)	Thickness T (mm)
MLF2012DR10J	0.1	±5%	20	400	0.15	300	0.85±0.2
MLF2012DR12J	0.12	±5%	20	360	0.20	300	0.85±0.2
MLF2012DR15J	0.15	±5%	20	320	0.20	300	0.85±0.2
MLF2012DR18J	0.18	±5%	20	280	0.25	300	0.85±0.2
MLF2012DR22J	0.22	±5%	20	250	0.30	250	0.85±0.2
MLF2012DR27J	0.27	±5%	20	220	0.35	250	0.85±0.2
MLF2012DR33J	0.33	±5%	20	200	0.40	250	0.85±0.2
MLF2012DR39J	0.39	±5%	25	180	0.45	200	0.85±0.2
MLF2012DR47J	0.47	±5%	25	160	0.50	200	1.25±0.2
MLF2012DR56J	0.56	±5%	25	150	0.55	150	1.25±0.2
MLF2012DR68J	0.68	±5%	25	140	0.60	150	1.25±0.2
MLF2012DR82J	0.82	±5%	25	130	0.65	150	1.25±0.2
MLF2012A1R0J	1.00	±5%	45	120	0.30	80	0.85±0.2
MLF2012A1R2J	1.20	±5%	45	110	0.35	80	0.85±0.2
MLF2012A1R5J	1.50	±5%	45	100	0.40	80	0.85±0.2
MLF2012A1R8J	1.80	±5%	45	90	0.45	80	0.85±0.2
MLF2012A2R2J	2.20	±5%	45	80	0.50	50	0.85±0.2
MLF2012A2R7J	2.70	±5%	45	70	0.55	50	1.25±0.2
MLF2012A3R3J	3.30	±5%	45	60	0.60	50	1.25±0.2
MLF2012A3R9J	3.90	±5%	45	55	0.65	30	1.25±0.2
MLF2012A4R7J	4.70	±5%	45	50	0.70	30	1.25±0.2
MLF2012E5R6J	5.6	±5%	50	45	0.60	15	1.25±0.2
MLF2012E6R8J	6.8	±5%	50	40	0.65	15	1.25±0.2
MLF2012E8R2J	8.2	±5%	50	35	0.70	15	1.25±0.2
MLF2012E100J	10.0	±5%	50	30	0.80	15	1.25±0.2
MLF2012E120J	12.0	±5%	50	25	0.90	15	1.25±0.2

#### TYPICAL ELECTRICAL CHARACTERISTICS Q vs. FREQUENCY CHARACTERISTICS



#### IMPEDANCE vs. FREQUENCY CHARACTERISTICS

